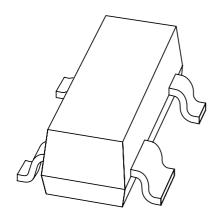
DISCRETE SEMICONDUCTORS

DATA SHEET



BAT74Schottky barrier double diode

Product specification Supersedes data of 1996 Mar 19 2001 Sep 05





Schottky barrier double diode

BAT74

FEATURES

- · Low forward voltage
- · Guard ring protected
- Small plastic SMD package.

APPLICATIONS

- Ultra high-speed switching
- · Voltage clamping
- · Protection circuits
- · Blocking diodes.

DESCRIPTION

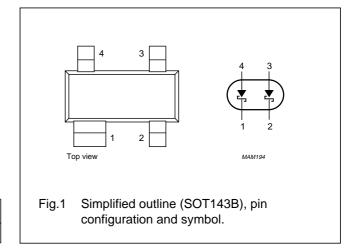
Planar Schottky barrier double diode. Two separate dies encapsulated in a SOT143B small plastic SMD package.

MARKING

TYPE NUMBER	MARKING CODE		
BAT74	L41		

PINNING

PIN	DESCRIPTION	
1	cathode (k ₁)	
2	cathode (k ₂)	
3	anode (a ₂)	
4	anode (a ₁)	



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode				•	
V_R	continuous reverse voltage		_	30	V
I _F	continuous forward current		_	200	mA
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ s}; \ \delta \le 0.5$	_	300	mA
I _{FSM}	non-repetitive peak forward current	t _p < 10 ms		600	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; see Fig.2	_	230	mW
T _{stg}	storage temperature		–65	+150	°C
T _j	junction temperature		_	125	°C
T _{amb}	operating ambient temperature		–65	+125	°C
Double diode operation					
V _R	continuous reverse voltage		_	30	V
		series connection	_	60	V
I _F	continuous forward current		_	110 ⁽¹⁾	mA
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ s; } \delta \le 0.5$	_	200	mA

Note

1. If both diodes are in forward operation at the same moment, total device current is max. 110 mA. If one diode is in reverse operation and the other is in forward operation at the same moment, total device current is max. 200 mA.

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Schottky barrier double diode

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOT143B standard mounting conditions.

ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

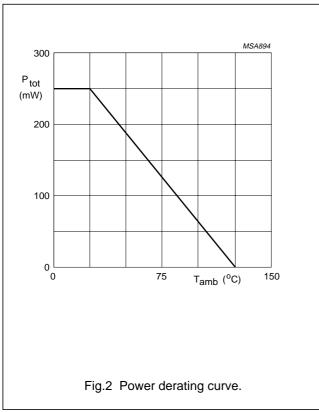
SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT	
Per diode					
V _F	forward voltage	see Fig.3			
		I _F = 0.1 mA	240	mV	
		I _F = 1 mA; note 1	320	mV	
		I _F = 10 mA	400	mV	
		I _F = 30 mA	500	mV	
		I _F = 100 mA	800	mV	
I _R	reverse current	V _R = 25 V; note 2; see Fig.4	2	μΑ	
t _{rr}	reverse recovery time	when switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω ; measured at I_R = 1 mA; see Fig.6	5	ns	
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; see Fig.5	10	pF	

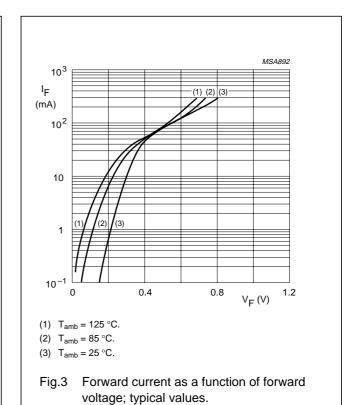
Notes

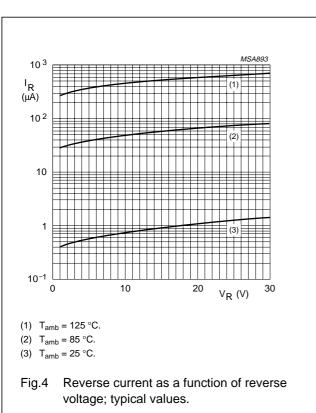
- 1. Temperature coefficient of forward voltage -0.6%/K.
- 2. Pulsed test: $t_p = 300\mu s$; $\delta = 0.02$.

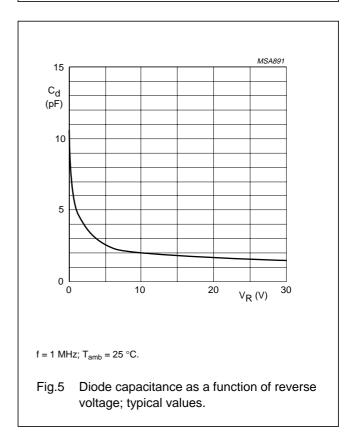
Schottky barrier double diode

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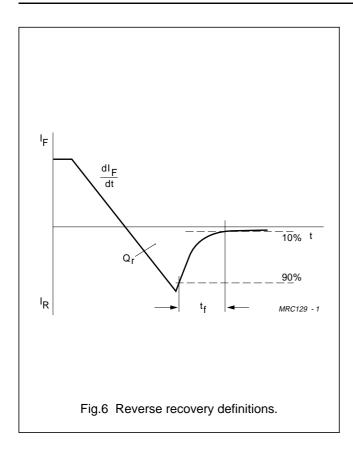




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Schottky barrier double diode

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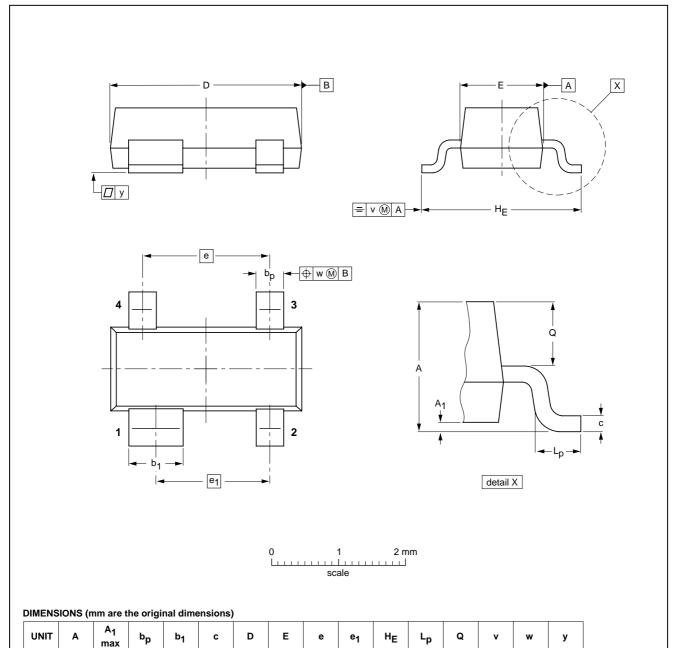
Schottky barrier double diode

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PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

SOT143B



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT143B						97-02-28

1.9

0.45

0.2

0.1

2001 Sep 05 6

0.48

mm

0.88

0.78

0.15

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Schottky barrier double diode

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DATA SHEET STATUS

DATA SHEET STATUS(1)	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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